

To: Journal of Materials Science: Materials in Electronics Editorial Board
Subject: Article Submit

Dear Editors,

Enclosed with this letter you will find an electronic submission of the manuscript entitled “Intensification of iron-boron complex association in silicon solar cells under acoustic wave action” by Oleg Olikh, Vitaliy Kostylyov, Victor Vlasiuk, Roman Korkishko, and Roman Chupryna. All authors have read and approved the final version submitted. No part of this paper has been published elsewhere. No conflict of interest exists in the submission of this manuscript.

The semiconductor structures are the base of electronics, and such structures’ properties are mainly determined by the defect subsystem. As a result, defect engineering is one of the most meaningful application tasks in semiconductor materials science. The irradiation and thermal treatment are ordinary ways to solve this problem. But the ultrasound showed abilities to affect defects as well. The present manuscript focuses on the experimental investigation of the influence of acoustic waves on admixture iron, which is a critical impurity in silicon-based technology. The acoustically driven acceleration of the iron-boron complex association has been revealed. We believe that using ultrasound for defect engineering would be interesting to the journal’s readers.

We would very much appreciate it if you would consider the manuscript for publication in the *Journal of Materials Science: Materials in Electronics*.

Sincerely yours,
Oleg Olikh and co-authors.
E-mail: olegolikh@knu.ua